

SEMICONDUCTOR PACKAGE

ABSTRACT OF THE DISCLOSURE

A semiconductor package with a flash-proof device is proposed, in which at least one chip and at least one passive device mounted on a substrate are covered by a flash-proof device dimensionally designed for positioning the substrate in a conventional mold and preventing a molding resin from flashing on the substrate in a molding process, and thus quality of the fabricated package can be assured. Due to no need of a specifically designed mold, fabrication costs are reduced. Furthermore, the flash-proof device has its top side exposed to outside of an encapsulant formed in the molding process, thereby allowing heat dissipating efficiency to be improved. Moreover, the flash-proof device provides shielding for the chip and the passive device received therein, so that external electromagnetic interference with performance of the semiconductor package can be reduced.

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